Switching Diode

The BAS16P2T5G Switching Diode is a spin-off of our popular SOT-23 three-leaded device. It is designed for switching applications and is housed in the SOD-923 surface mount package. This device is ideal for low-power surface mount applications, where board space is at a premium.

Features

 These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V _R	100	Vdc
Peak Forward Current	lF	200	mAdc
Peak Forward Surge Current	I _{FM(surge)}	500	mAdc

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

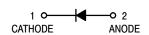
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient (Note 1) Total Power Dissipation @ T _A = 25°C	R _{θJA}	520	°C/W
	P _D	240	mW
Thermal Resistance, Junction-to-Ambient (Note 2) Total Power Dissipation @ T _A = 25°C	R _{θJA}	175	°C/W
	P _D	710	mW
Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

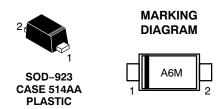
- 1. Mounted onto a 4 in square FR–4 board 10 mm sq. 1 oz. Cu $0.06^{\prime\prime}$ thick single sided. Operating to steady state.
- Mounted onto a 4 in square FR-4 board 1 in sq. 1 oz. Cu 0.06" thick single sided. Operating to steady state.



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A6 = Specific Device Code M = Month Code

ORDERING INFORMATION

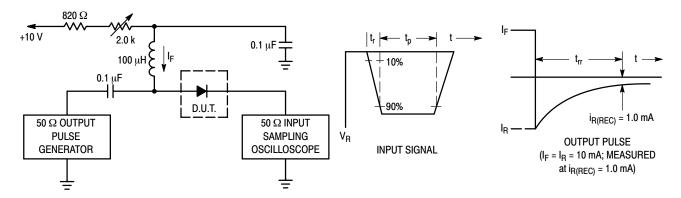
Device	Package	Shipping [†]
BAS16P2T5G	SOD-923 (Pb-Free)	8000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit		
OFF CHARACTERISTICS						
Reverse Voltage Leakage Current $ \begin{array}{l} (V_R=75~\text{Vdc}) \\ (V_R=100~\text{Vdc}) \\ (V_R=75~\text{Vdc},~T_J=150^\circ\text{C}) \\ (V_R=25~\text{Vdc},~T_J=150^\circ\text{C}) \end{array} $	I _R	- - -	1.0 100 50 30	μAdc		
Reverse Breakdown Voltage (I _{BR} = 100 μAdc)	V _(BR)	100	-	Vdc		
Forward Voltage ($I_F = 1.0 \text{ mAdc}$) ($I_F = 10 \text{ mAdc}$) ($I_F = 50 \text{ mAdc}$) ($I_F = 150 \text{ mAdc}$)	V _F	- - -	715 855 1000 1250	mV		
Diode Capacitance (V _R = 0, f = 1.0 MHz)	C _D	_	2.0	pF		
Forward Recovery Voltage (I _F = 10 mAdc, t _r = 20 ns)	V _{FR}	-	1.75	Vdc		
Reverse Recovery Time (I _F = I _R = 10 mAdc, R _L = 50 Ω)	t _{rr}	-	6.0	ns		
Stored Charge (I _F = 10 mAdc to V _R = 5.0 Vdc, R _L = 500 Ω)	Qs	ı	45	pC		



Notes: 1. A 2.0 k Ω variable resistor adjusted for a Forward Current (I_F) of 10 mA.

- 2. Input pulse is adjusted so I_{R(peak)} is equal to 10 mA.
- 3. t_p » t_{rr}

Figure 1. Recovery Time Equivalent Test Circuit

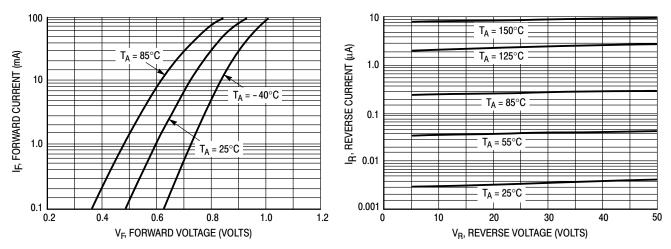


Figure 2. Forward Voltage

Figure 3. Leakage Current

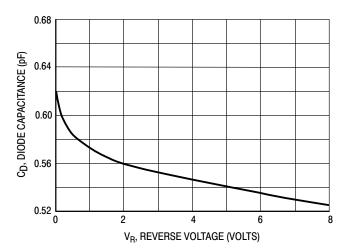
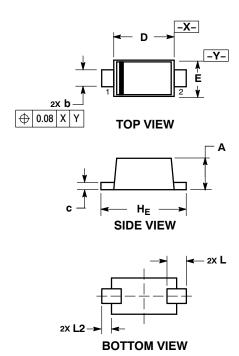


Figure 4. Capacitance

PACKAGE DIMENSIONS

SOD-923 CASE 514AA ISSUE E



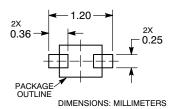
NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS.
- CONTROLLING DIMENSION: MILLIMETERS.MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE
- MINIMUM THICKNESS OF BASE MATERIAL

 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.34	0.39	0.43	0.013	0.015	0.017
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
HE	0.95	1.00	1.05	0.037	0.039	0.041
L	0.19 REF			0.007 REF		
L2	0.05	0.10	0.15	0.002	0.004	0.006

SOLDERING FOOTPRINT*



See Application Note AND8455/D for more mounting details

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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